

R35-2010BB100R0Fx1QG

◆ Product Features

Case Size	Std. Resistance	Power
2010 mils	100Ω	250 mW

◆ Specifications

Operating Frequency	DC to 50 GHz
Insertion Loss	6.0 dB ± 2dB typical
Operating Temperature Range	55°C to +150°C
Resistive Material	Tantalum Nitride (TaN)
Temperature Coefficient	±150 ppm/°C standard
Resistance Tolerance	±1% (other tolerances available)
Substrate	Alumina (Al ₂ O ₃); other substrates available
Metallization	A = Tantalum/Palladium/Gold (TaN/Pd/Au) R = Titanium/Platinum/Gold (Ti/Pt/Au)

◆ Packaging

Parts are available in Waffle Packs and Tape & Reel. Contact PPI for additional packaging options.

◆ Mechanical Dimensions

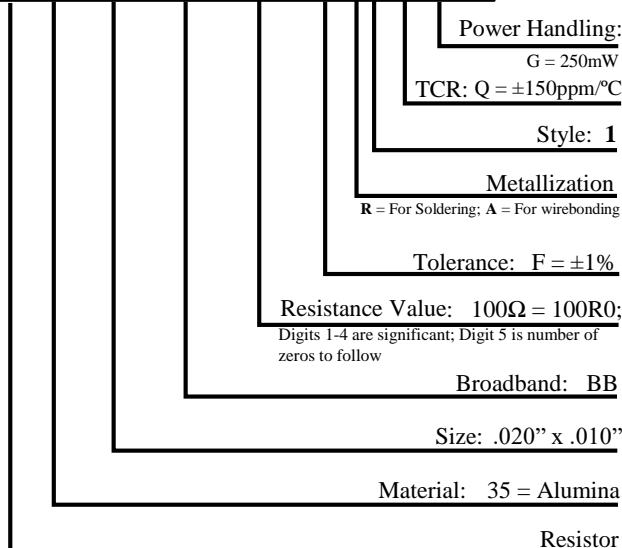
L = 0.020" ± 0.002" (0.508mm ± 0.051mm)
W = 0.010" ± 0.001" (0.254mm ± 0.051mm)
H = 0.010" ± 0.001" (0.254mm ± 0.025mm)

◆ Test Conditions

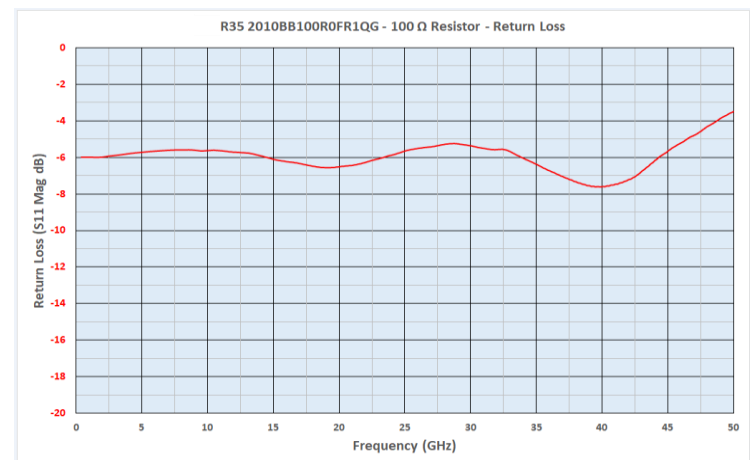
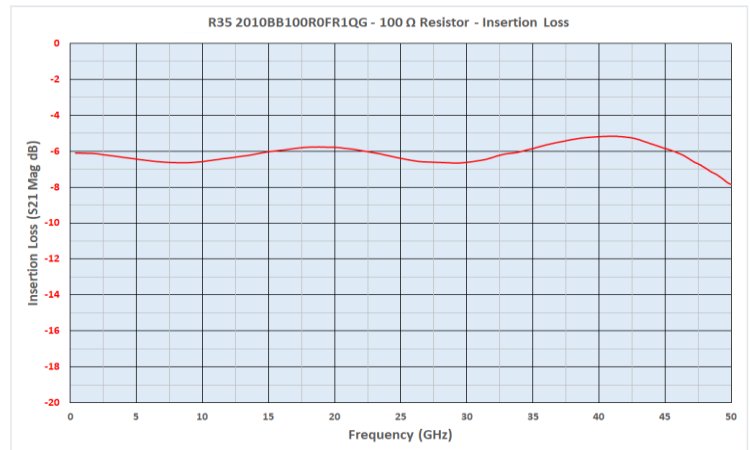
Resistors were measured using 6.6 mil thick RO4350, using typical TRL calibration.

◆ Part Numbering

R 35-2010 BB 100R0 F R1 Q G



◆ Performance Curves— Insertion and Return Loss Charts



Style: 1 – Recessed Pad

Best for wire bonding or surface mount applications; compatible with Flip Chip configuration.

